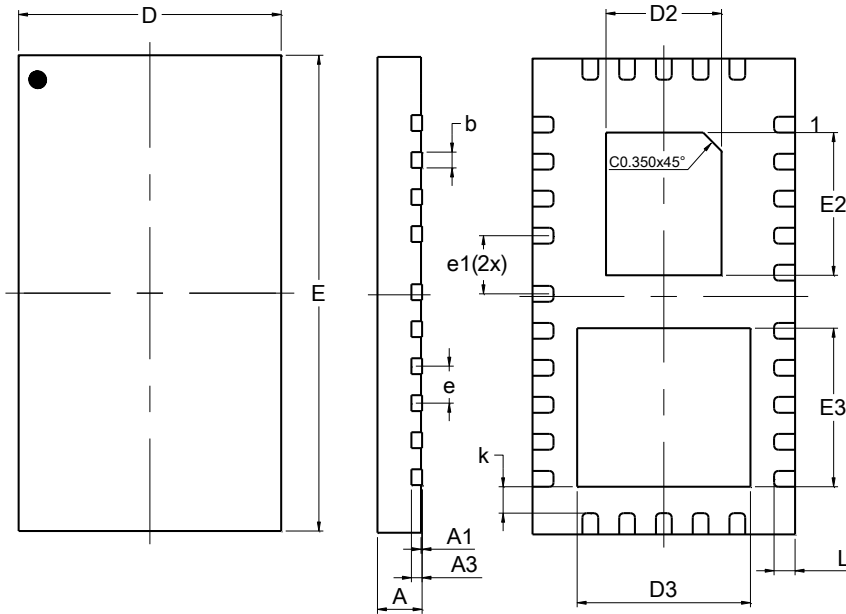


Package Outline Dimensions

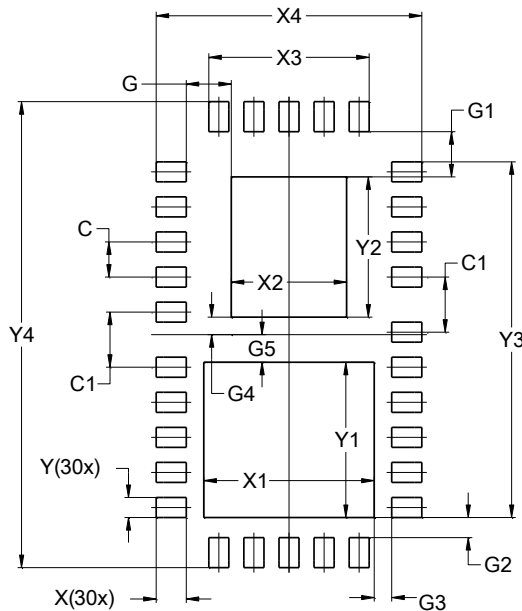
V-QFN5090-30 (Type A1)



V-QFN5090-30 (Type A1)			
Dim	Min	Max	Typ
A	0.80	0.90	0.85
A1	0.00	0.05	0.02
A3	0.203 REF		
b	0.25	0.35	0.30
D	5.00 BSC		
D2	2.15	2.25	2.20
D3	3.25	3.35	3.30
E	9.00 BSC		
E2	2.65	2.75	2.70
E3	2.95	3.05	3.00
e	0.70 BSC		
e1	1.10 BSC		
k	0.20	--	--
L	0.35	0.45	0.40
All Dimensions in mm			

Suggested Pad Layout

V-QFN5090-30 (Type A1)



Dimensions	Value (in mm)
C	0.700
C1	1.100
G	0.900
G1	0.900
G2	0.400
G3	0.350
G4	0.350
G5	0.550
X	0.600
X1	3.400
X2	2.300
X3	3.200
X4	5.300
Y	0.400
Y1	3.100
Y2	2.800
Y3	7.100
Y4	9.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.